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Substitute for form 1449A/PTO				Complete If Known	
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>				Application Number	10/776,076
				Filing Date	February 10, 2004
				First Named Inventor	Madhav Datta
				Art Unit	2813
				Examiner Name	Thanhha S. Pham
Sheet	3	of	3	Attorney Docket Number	42P11468D

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No.†	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T*
TSP		"Chromium Copper Step Phasing", IBM Technical Disclosure Bulletin, (08/01/1977), pgs. 1005-1006	
TSP		TUMMALA, RAO et al., "Microelectronics Packaging Handbook, Semiconductor Packaging", Part 2, 2nd Edition, (1997), pgs. 132-139	
TSP		Annala, P., et al., "Electroplated Solder Alloys for Flip Chip Interconnections", Physica Scripta, T69, pp. 115-118 (1997)	
TSP		Datta, M., et al. "Electrochemical Fabrication of Mechanically Robust PbSn C4 Interconnection", Journal of the Electrochemical Society, 142 (11), 7 p., (Nov 1995)	
TSP		Honma, S., et al. "Effectiveness of Thin-Film Barrier Metals for Eutectic Solder Bumps", Microelectronics International, 14 (3), pp. 47-50 (Sept. 1997)	
TSP		Liu, C.Y., et al., "Electron microscopy study of interfacial reaction between eutectic SnPb and Cu/Ni (v)/Al thin film metallization", Journal of Applied Physics, 86 (1), pp. 1-5 (Dec. 1999), pp. 750-754	

Jan. 15, 2000

Examiner Signature		Date Considered	7/18/05
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\*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication.

†Applicant's unique citation designation number. Applicant is to place a check mark here if English language Translation is attached.

Based on PTO/SB/088 (08-03) as modified by Blakely, Solokoff, Taylor & Zafman (w/r) 08/11/2003.  
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